

Specification of Thermoelectric Module

TEHC1-127018

Description

The 127 couples, 40 mm × 40 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74°C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- High effective cooling and efficiency.
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

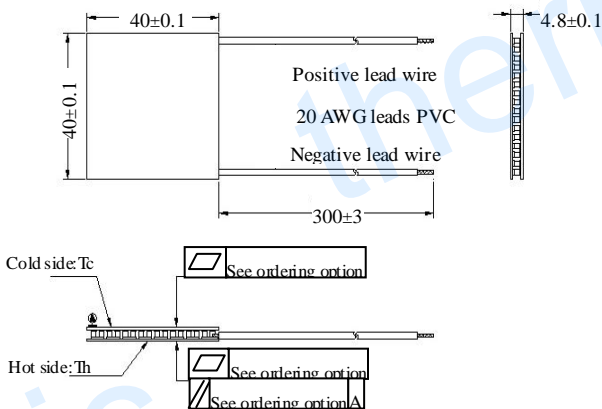
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th(°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	16.8	18.2	Voltage applied to the module at DT _{max}
I _{max} (amps)	3.03	3.03	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	31.7	34.1	Cooling capacity at cold side of the module under DT=0 °C
AC resistance(ohms)	4.2	4.5	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:

1. T100: BiSn (Melting Point=138°C)
2. T200: CuSn (Melting Point= 227 °C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

C. Ceramics:

1. Alumina (Al₂O₃, white 96%)(AIO)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized (Copper-Nickel plating)

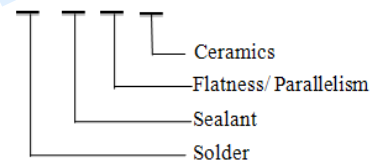
Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:4.8±0.1	0:0.05/0.05	300±3/Specify
TF	1:4.8±0.05	1:0.025/0.025	300±3/Specify
TF	2:4.8±0.025	2:0.015/0.015	300±3/Specify

Eg. TF01: Thickness 4.8±0.1(mm) and Flatness 0.025/0.025(mm)

Naming for the Module

TEHC1- 127018- X - X - X - X



TEHC1- 127018- T100 -SS - TF01- AIO

T100: Solder, BiSn (MeltingPoint=138 °C)

SS: Silicone sealing

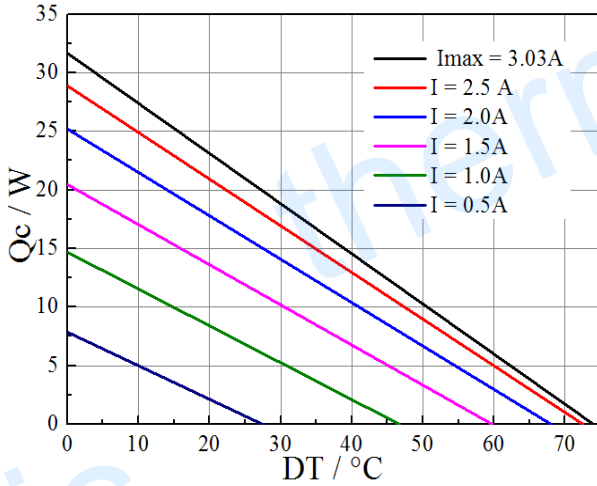
AIO: Alumina white 96%

TF01: Thickness ±0.1(mm) and Flatness/Parallelism 0.025/0.025(mm)

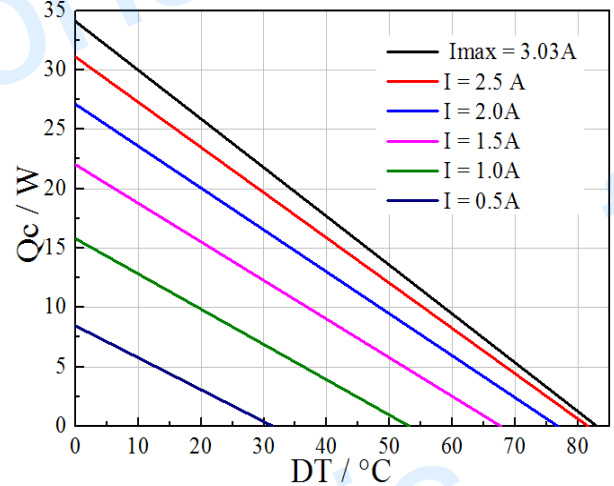
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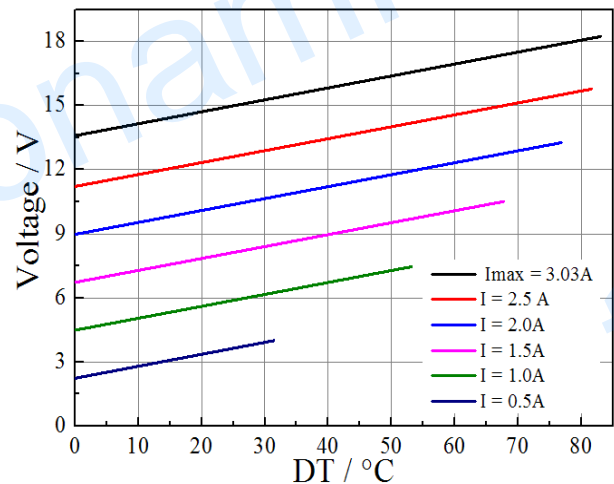
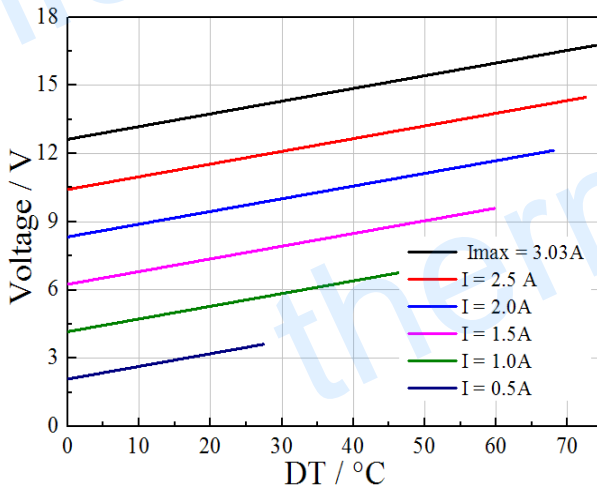
Performance Curves at $T_h=27\text{ }^\circ\text{C}$



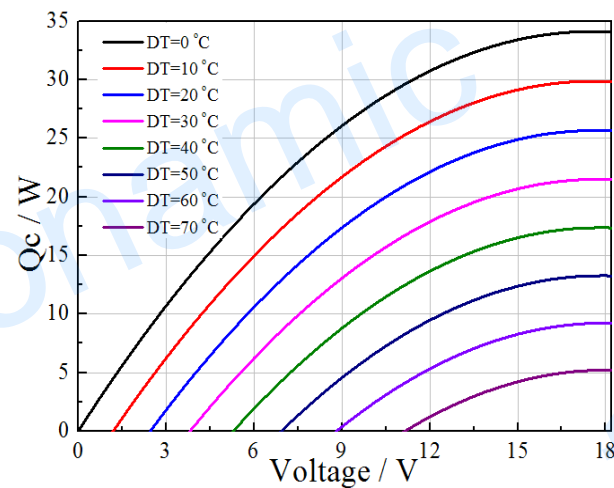
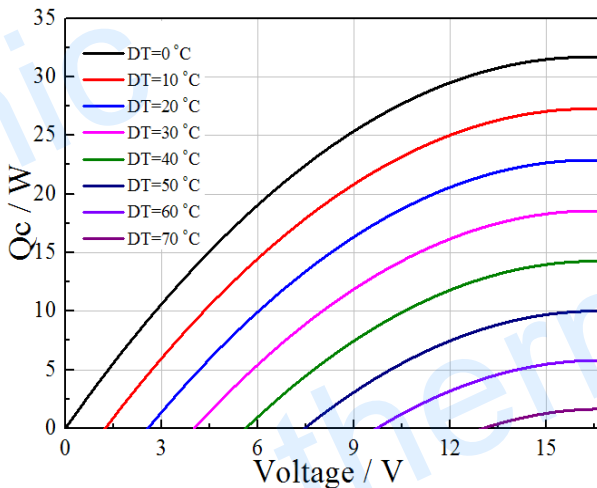
Performance Curves at $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(\Delta T)$

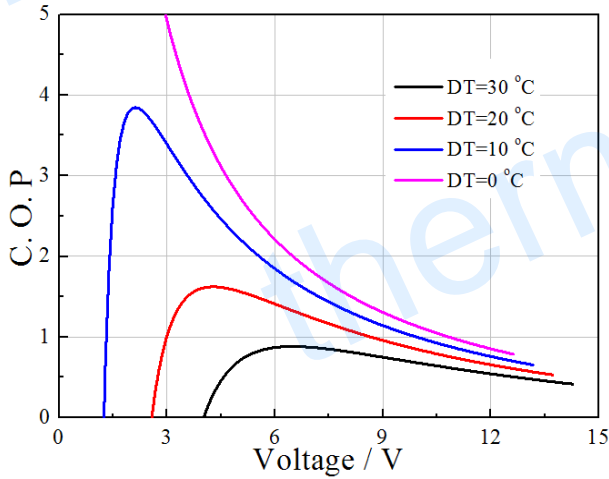


Standard Performance Graph $Q_c = f(V)$

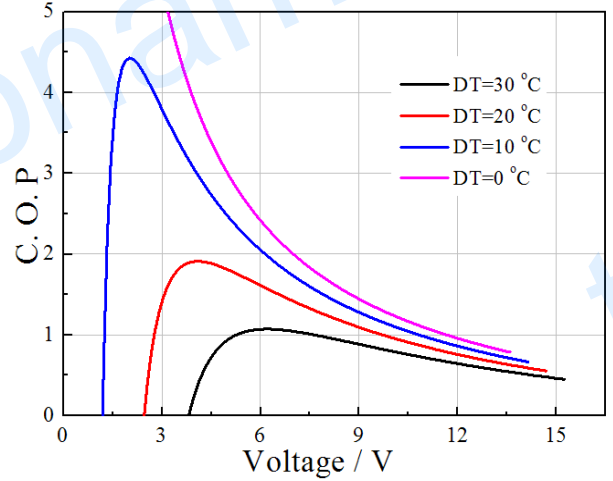
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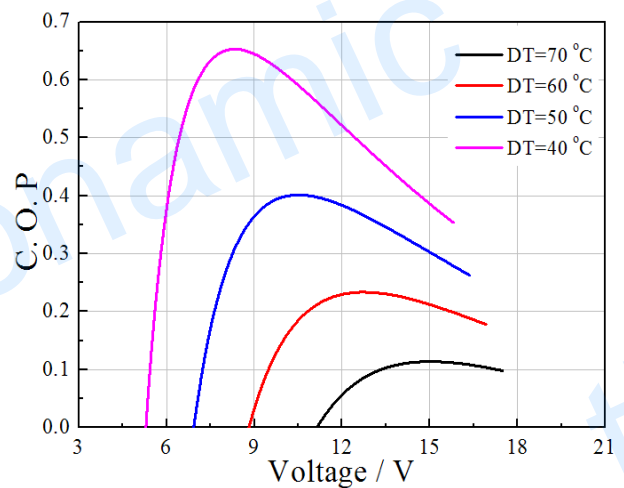
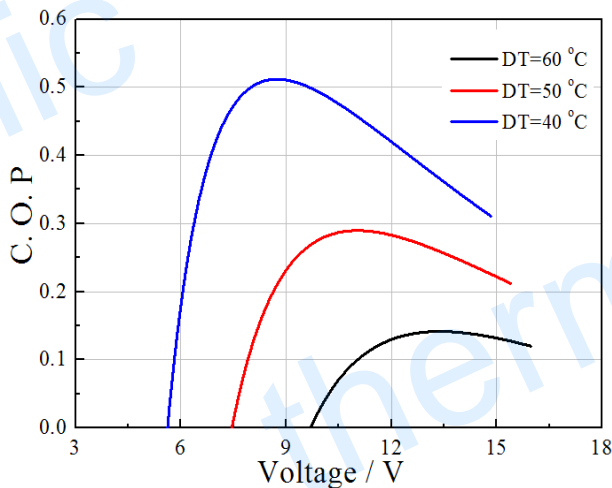
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Cold side of the module stucked on the object being cooled
- Operation below I_{max} or V_{max}
- Hot side of the module mounted on a heat radiator
- Operation or storage module below 100 °C
- Work under DC